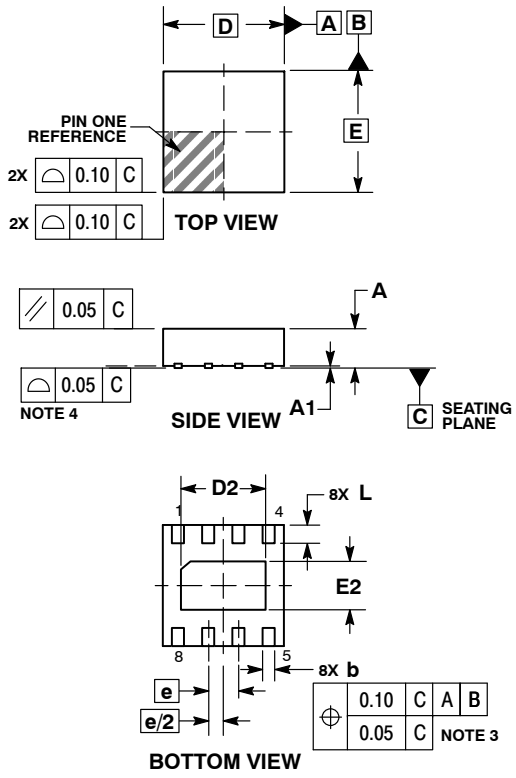
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

SCALE 2:1

CUDFN8, 2x2, 0.5P
CASE 505AP
ISSUE O

DATE 19 DEC 2016



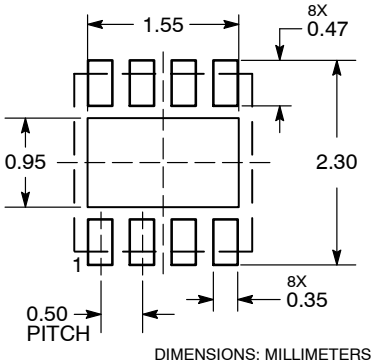
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS	
DIM	MIN	MAX
A	0.55	0.65
A1	0.00	0.05
b	0.20	0.30
D	2.00 BSC	
D2	1.30	1.50
E	2.00 BSC	
E2	0.70	0.90
e	0.50 BSC	
L	0.25	0.35

GENERIC MARKING DIAGRAM*

(*Note: Clear package, no marking is present)

RECOMMENDED MOUNTING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	**CUDFN8 2X2, 0.5P**	**PAGE 1 OF 1**